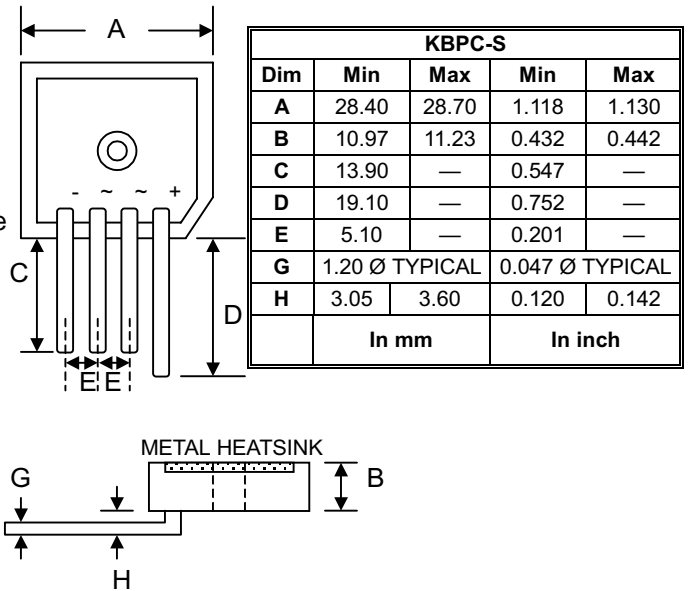


Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- Designed for Saving Mounting Space
- UL Recognized File # E223064
- Green Products in Compliance with the RoHS Directive

Mechanical Data

- Case: Epoxy Case with Heat Sink Internally Mounted in the Bridge Encapsulation
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 30 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

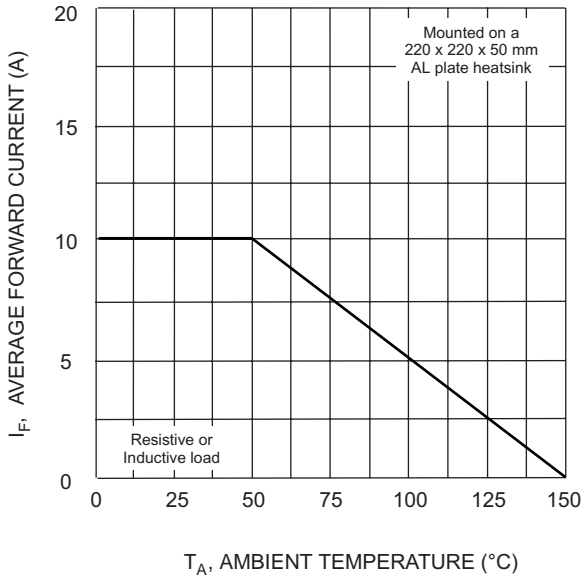


Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

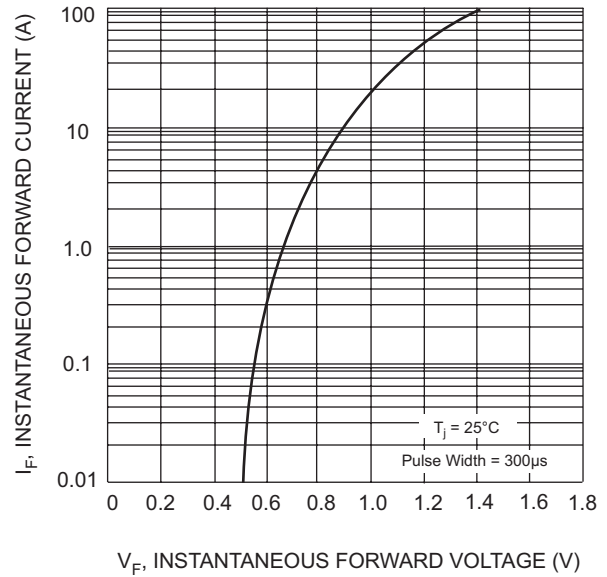
Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	GBPC 1000S-G	GBPC 1001S-G	GBPC 1002S-G	GBPC 1004S-G	GBPC 1006S-G	GBPC 1008S-G	GBPC 1010S-G	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V_{RWM}								
DC Blocking Voltage	V_R								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_A = 50^{\circ}\text{C}$	I_o	10							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	200							A
Forward Voltage (per element) @ $I_F = 5.0\text{A}$	V_{FM}	1.1							V
Peak Reverse Current @ $T_C = 25^{\circ}\text{C}$ At Rated DC Blocking Voltage @ $T_C = 125^{\circ}\text{C}$	I_R	5.0 500							μA
Rating for Fusing ($t < 8.3\text{ms}$) (Note 1)	$I^2 t$	374							A^2s
Typical Thermal Resistance (Note 2)	$R_{\theta JC}$	2.0							K/W
RMS Isolation Voltage from Case to Lead	V_{ISO}	2500							V
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +150							$^{\circ}\text{C}$

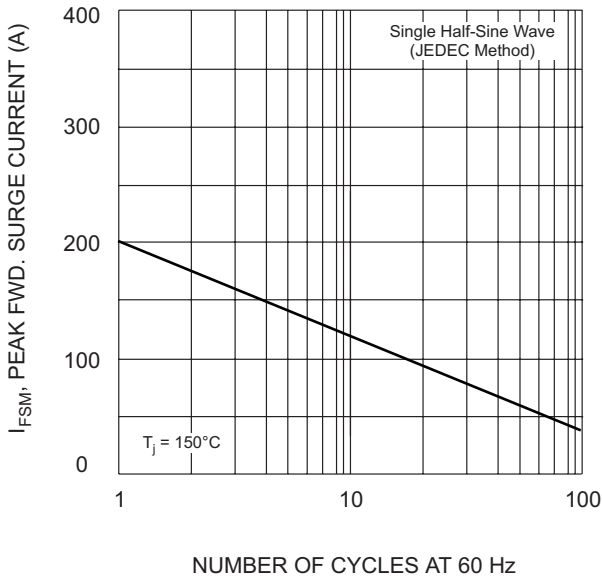
Note: 1. Non-repetitive for $t > 1\text{ms}$ and $< 8.3\text{ms}$.
2. Thermal resistance junction to case per element mounted on 220 x 220 x 50mm thick AL plate.



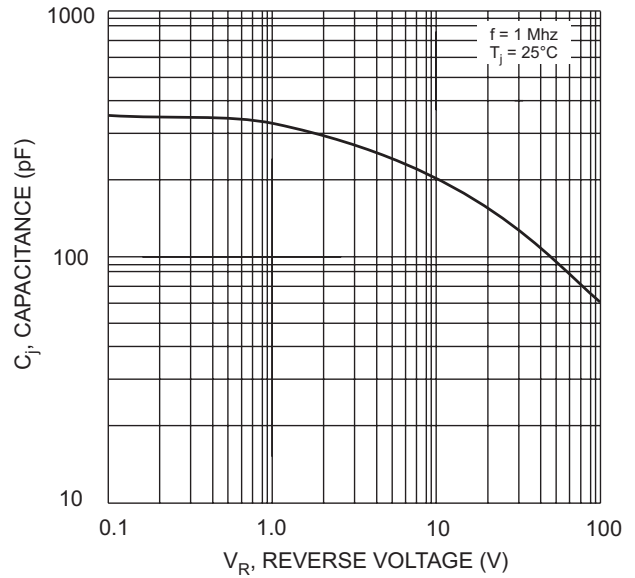
T_A , AMBIENT TEMPERATURE (°C)
Fig. 1 Forward Current Derating Curve



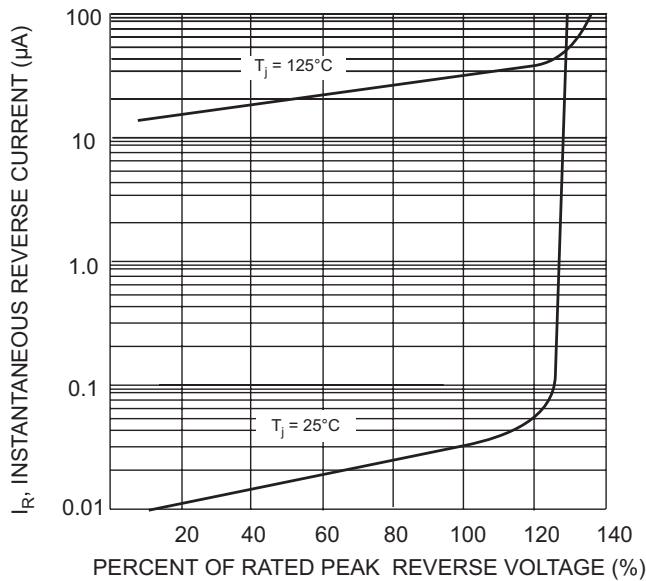
V_F , INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 2 Typical Forward Characteristics (per element)



NUMBER OF CYCLES AT 60 Hz
Fig. 3 Max Non-Repetitive Surge Current



V_R , REVERSE VOLTAGE (V)
Fig. 4 Typical Junction Capacitance (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)
Fig. 5 Typical Reverse Characteristics (per element)

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